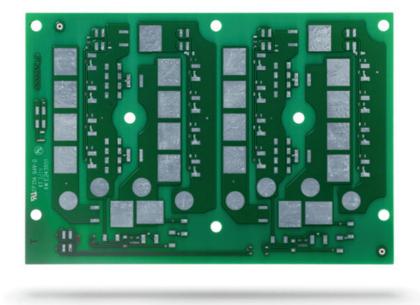


3 PUKI

Multilayer HDI RF IMS Flexible Rigid-Flex Semi-Flex Double sided

May 2016



IMS - Insulated Metal Base

NCAB has approved factories that are specialists in this field, with plants dedicated to IMS products, supporting sectors including automotive, medical, aerospace, lightning applications and industrial controls. This is a segment that is growing rapidly and our spend is increasing month by month.

IMS PCBs – TECHNICAL SPECIFICATION

FEATURE	NCAB'S TECHNICAL SPECIFICATION
Number of layers	1 – 4 layers
Technology highlights	Effective heat sink solutions for thermal applications. This construction type enables superior heat dissipation through use of either aluminium or copper substrate bonded to the insulated circuitry through thermal pre-preg or resin systems.
Materials	Aluminium & copper plates. FR-4, PTFE, thermal dielectrics
Dielectric thickness	0.05mm – 0.20mm
Thermal conductivity	3 (W/(m·K))
Profile method	Punching, Liquid cooled routing
Copper weights (finished)	35um – 140um
Minimum track and gaps	0.10mm / 0.10mm
Metal core thickness	0.40mm – 3.20mm
Maximum dimensions	550mm x 700mm
Surface finishes available	HASL, LF HASL, OSP, ENIG, Immersion tin, Immersion silver
Minimum mechanical drill	0.30mm